

**Amendments to the Claims:**

This listing of claims replaces all prior versions, and listings, of claims in this application.

**Listing of Claims:**

1-17. (Canceled)

18. (Previously presented) A probe for a probe card characterized in that the same has a structure where either nickel plating or nickel alloy plating is applied to the surface of a core material made of a metal alloy and then a wire drawing operation with a wire drawing die is performed, wherein the probe sustains a substantially higher contact force as compared to a probe made of metal alloy wire that is not subject to the wire drawing operation.

19. (Previously presented) The probe for a probe card of claim 18, wherein the metal alloy comprises one of: a palladium alloy and a copper beryllium alloy.

20. (Previously presented) The probe for a probe card of claim 18, wherein the probe has a substantially superior spring characteristic and hardness as compared to a probe made of metal alloy wire that is not subject to the wire drawing operation.

21. (New) A probe for a probe card comprising drawn wire, the drawn wire comprising:  
a core material containing at least one of palladium alloy and copper beryllium alloy; and

a plating material containing at least one of nickel plating and nickel alloy plating.

22. (New) The probe for a probe card according to claim 21, wherein a second plating material comprising a gold plating is applied to an upper-most surface of said probe after a wire drawing operation is performed.

23. (New) The probe for a probe card according to claim 21, wherein the probe can be applied for performing an inspection of an IC chip having an inter-electrode pitch size of approximately 100  $\mu\text{m}$ .

24. (New) The probe for a probe card according to claim 21, wherein the probe is approximately 65  $\mu\text{m}$  in diameter.

25. (New) The probe for a probe card according to claim 24, whereby positional displacement with respect to the IC chip electrode is minimized.

26. (New) The probe for a probe card according to claim 21, wherein a thickness of the plating material is about 3 – 15  $\mu\text{m}$ .

27. (New) The probe for a probe card according to claim 22, wherein thickness of the gold plating is about 0.2 – 1.0  $\mu\text{m}$ .

28. (New) A method for fabricating a probe used for measuring small pitch components, comprising:
- forming a wire using a core material having an initial core diameter;
  - plating the core material with a plating material having an initial plating thickness to form an initial wire diameter;
  - drawing the wire through one or more dies, wherein a final probe wire diameter is substantially smaller than the initial diameter.
29. (New) The method of claim 28, wherein the drawing the wire through one or more dies comprises drawing the wire through a plurality of dies, wherein a rate of cross-sectional area reduction when the wire is drawn through a die is about 10-20%.
30. (New) The method of claim 28, wherein the initial core diameter is about 100  $\mu\text{m}$ , and wherein the plating thickness is about 2 to 15  $\mu\text{m}$ .
31. (New) The method of claim 30, wherein the final probe wire diameter is about 65  $\mu\text{m}$ .

32. (New) The method of claim 28, wherein the wire material comprises at least one of palladium alloy and copper beryllium alloy, and wherein the plating material comprises at least one of nickel and nickel alloy.

33. (New) The method of claim 28, further comprising applying a gold plating to the wire after the drawing the wire through the one or more dies.